

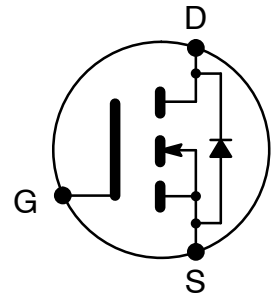


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**NTE2395
 MOSFET
 N-Ch, Enhancement Mode
 High Speed Switch
 TO220 Type Package**

Features:

- Dynamic dv/dt Rating
- +175°C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements



Absolute Maximum Ratings:

Continuous Drain Current ($V_{GS} = 10V$), I_D	
$T_C = +25^\circ C$ (Note 1)	50A
$T_C = +100^\circ C$	36A
Pulsed Drain Current (Note 2), I_{DM}	200A
Power Dissipation ($T_C = +25^\circ C$), P_D	150W
Derate Linearly Above $25^\circ C$	1.0W/ $^\circ C$
Gate-to-Source Voltage, V_{GS}	$\pm 20V$
Single Pulse Avalanche Energy (Note 3), E_{AS}	100mJ
Peak Diode Recovery dv/dt (Note 4), dv/dt	4.5V/ns
Operating Junction Temperature Range, T_J	-55° to $+175^\circ C$
Storage Temperature Range, T_{stg}	-55° to $+175^\circ C$
Lead Temperature (During Soldering, 1.6mm from case for 10sec), T_L	$+300^\circ C$
Mounting Torque (6-32 or M3 Screw)	10 lbf•in (1.1N•m)
Thermal Resistance, Junction-to-Case, R_{thJC}	1.0 $^\circ C/W$
Thermal Resistance, Junction-to-Ambient, R_{thJA}	62 $^\circ C/W$
Typical Thermal Resistance, Case-to-Sink (Flat, Greased Surface), R_{thCS}	0.5 $^\circ C/W$

Note 1. Current limited by the package, (Die Current = 51A).

Note 2. Repetitive rating; pulse width limited by maximum junction temperature.

Note 3. $V_{DD} = 25V$, starting $T_J = +25^\circ C$, $L = 44 \leq H$, $R_G = 25 \pm$, $I_{AS} = 51A$

Note 4. $I_{SD} \leq 51A$, $di/dt \leq 250A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq +175^\circ C$

Electrical Characteristics: ($T_J = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	60	-	-	V
Breakdown Voltage Temp. Coefficient	$\frac{V_{(BR)DSS}}{T_J}$	Reference to $+25^\circ\text{C}$, $I_D = 1\text{mA}$	-	0.060	-	V/ $^\circ\text{C}$
Static Drain-to-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 31A$, Note 5	-	-	0.028	\pm
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	-	4.0	V
Forward Transconductance	g_{fs}	$V_{DS} = 25V, I_D = 31A$, Note 5	15	-	-	mhos
Drain-to-Source Leakage Current	I_{DSS}	$V_{DS} = 60V, V_{GS} = 0V$	-	-	25	$\leq\text{A}$
		$V_{DS} = 48V, V_{GS} = 0V, T_J = +125^\circ\text{C}$	-	-	250	$\leq\text{A}$
Gate-to-Source Forward Leakage	I_{GSS}	$V_{GS} = 20V$	-	-	100	nA
Gate-to-Source Reverse Leakage	I_{GSS}	$V_{GS} = -20V$	-	-	-100	nA
Total Gate Charge	Q_g	$I_D = 51A, V_{DS} = 48V, V_{GS} = 10V$, Note 5	-	-	67	nC
Gate-to-Source Charge	Q_{gs}		-	-	18	nC
Gate-to-Drain ("Miller") Charge	Q_{gd}		-	-	25	nC
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30V, I_D = 51A, R_G = 9.1\pm,$ $R_D = 0.55\pm$, Note 5	-	14	-	ns
Rise Time	t_r		-	110	-	ns
Turn-Off Delay Time	$t_{d(off)}$		-	45	-	ns
Fall Time	t_f		-	92	-	ns
Internal Drain Inductance	L_D	Between lead, .250in. (6.0) mm from package and center of die contact	-	4.5	-	nH
Internal Source Inductance	L_S		-	7.5	-	nH
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1\text{MHz}$	-	1900	-	pF
Output Capacitance	C_{oss}		-	920	-	pF
Reverse Transfer Capacitance	C_{riss}		-	170	-	pF

Source-Drain Ratings and Characteristics:

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	I_S	Note 1	-	-	50	A
Pulsed Source Current (Body Diode)	I_{SM}	Note 2	-	-	200	A
Diode Forward Voltage	V_{SD}	$T_J = +25^\circ\text{C}, I_S = 51A, V_{GS} = 0V$, Note 5	-	-	2.5	V
Reverse Recovery Time	t_{rr}	$T_J = +25^\circ\text{C}, I_F = 51A$, $di/dt = 100A/\mu\text{s}$, Note 5	-	120	180	ns
Reverse Recovery Charge	Q_{rr}		-	0.53	0.80	$\leq\text{C}$
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Note 1. Current limited by the package, (Die Current = 51A).

Note 2. Repetitive rating; pulse width limited by maximum junction temperature.

Note 5. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

